

**PATENT ASSIGNMENT**

Electronic Version v1.1  
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Meng-Jen Wang</td> <td>05/02/2007</td> </tr> <tr> <td>Kuo-Pin Yang</td> <td>05/02/2007</td> </tr> <tr> <td>Wei-Min Hsiao</td> <td>05/02/2007</td> </tr> <tr> <td>Sheng-Yang Peng</td> <td>05/02/2007</td> </tr> </tbody> </table>		Name	Execution Date	Meng-Jen Wang	05/02/2007	Kuo-Pin Yang	05/02/2007	Wei-Min Hsiao	05/02/2007	Sheng-Yang Peng	05/02/2007
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<b>RECEIVING PARTY DATA</b>											
<b>Name:</b>	Advanced Semiconductor Engineering, Inc.										
<b>Street Address:</b>	26 Chin 3rd Rd., Nantze Export Processing Zone										
<b>City:</b>	Kao-Hsiung City										
<b>State/Country:</b>	TAIWAN										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11772243</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11772243						
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Application Number:	11772243										
<b>CORRESPONDENCE DATA</b>											
<b>Fax Number:</b>	(703)997-4517										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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<b>ATTORNEY DOCKET NUMBER:</b>	ASEP0074USA										
<b>NAME OF SUBMITTER:</b>	WINSTON HSU										
<b>Total Attachments: 2</b> source=ASEP0074USA0_A1_1_NP005#page1.tif source=ASEP0074USA0_A1_1_NP005#page2.tif											

CH \$40.00 11772243

**PATENT**

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Meng-Jen Wang Nationality: R.O.C.

Name: Kuo-Pin Yang Nationality: R.O.C.

Name: Wei-Min Hsiao Nationality: R.O.C.

Name: Sheng-Yang Peng Nationality: R.O.C.

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: Advanced Semiconductor Engineering, Inc.

Address: 26 Chin 3rd Rd., Nantze Export Processing Zone, Kao-Hsiung City, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"SEMICONDUCTOR PACKAGING STRUCTURE HAVING ELECTROMAGNETIC SHIELDING FUNCTION AND METHOD FOR MANUFACTURING THE SAME"**

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this \_\_\_\_\_ (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Meng-Jen Wang

Meng-Jen Wang 5/2/07

Kuo-Pin Yang

Kuo-Pin Yang 5/2/07

Wei-Min Hsiao

Wei-Min Hsiao 5/2/2007

Sheng-Yang Peng

Sheng-Yang Peng 5/2, 07